

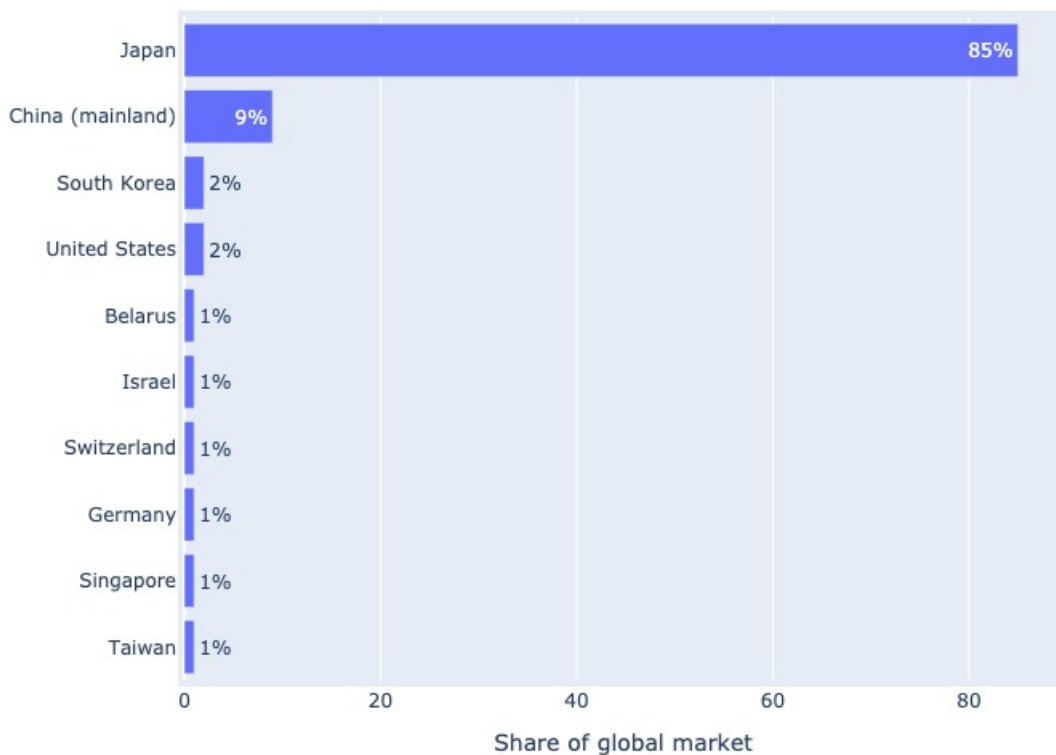
Supply Chain Explorer: Dicing tools

This is an export from the Emerging Technology Observatory **Supply Chain Explorer** (<https://chipexplorer.eto.tech>). You can see the web version of this content at <https://chipexplorer.eto.tech/?filter-choose=input-resource&input-resource=N71>.

Dicing tools

Dicing tools cut individual chips (dies) in the wafer into separated chips. This process also involves thinning the wafer. Dicing tools include blade saws, laser saws, dicing accessories and backside grinding equipment.

Supplier countries



Notable supplier companies

- ASM Pacific - China (mainland)
- Accretech - Japan
- Disco - Japan
- Longhill Industries - China (mainland)
- SYNOVA - China (mainland)